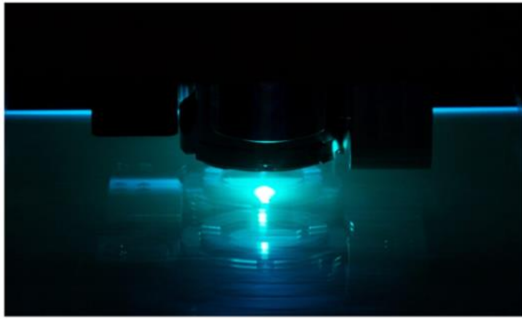
Member of the Week – July 15, 2022

IFTLE 526: NIST Funds SEMI/UCLA CHIPS HIR Roadmap

The UCLA Center for Heterogeneous Integration and Performance Scaling (UCLA CHIPS) and SEMI have announced that they have been awarded a $0.3MM grant from NIST to produce a roadmap for advancing heterogeneous integration and advanced packaging technologies in the US. This is one of the first awards by NIST's Advanced Manufacturing Technology Roadmap Program, and will fund the project for 18 months.

READ MORE



Maskless Lithography Addresses Shift Toward Heterogeneous Integration and 3D Packaging

READ POST

ECTC 2022: Amazing In-person Packaging Community Participation!

READ POST

Lam Research Year in Review

WATCH VIDEO

The Importance of Building Trusted and Secure Microelectronics

LISTEN HERE

Member of the Week

EV Group (EVG) is a long-time leader in providing wafer bonding and lithography equipment for the MEMS, nanotechnology, and semiconductor markets. Key products include wafer bonding, thin-wafer processing, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners, and inspection systems. This week, the company announced a major breakthrough in die-to-wafer (D2W) fusion and hybrid bonding by successfully demonstrating 100-percent void-free bonding yield of multiple dies of different sizes from a complete 3D system-on-a-chip (SoC) in a single transfer process using its GEMINI®FB automated hybrid bonding system. This important industry achievement was carried out at EVG's Heterogeneous Integration Competence Center™ (HICC), which is designed to assist customers in leveraging EVG's process solutions and expertise to accelerate the development of new and differentiating products and applications driven by advances in system integration and packaging.

LEARN MORE

Community News

EV Group Achieves Die-to-Wafer Fusion and Hybrid Bonding Milestone with 100-Percent Die Transfer Yield on Multi-Die 3D System-on-a-Chip

MRSI Launches New Die Bonder with Improved Throughput for High Power Laser Manufacturers

Onto Innovation Announces the Latest Addition to its Family of Acoustic Metrology Products

Recommended Reads

Customization, Heterogenous Integration, And Brute Force Verification – SemiEngineering

Events

IEEE IEDM 2022 Call for Papers July 14 Deadline

9th ESTC (Electronics System-Integration Technology Conference)
September 13-16

Looking to Advertise?
Click here to access the 3D InCites Media Kit